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**Amendments to the Claims:**

This listing of claims will replace all prior versions and listings of claims in the Application:

**Listing of Claims:**

1. – 14. (cancelled)

15. (currently amended) A method for manufacturing an assembly including a printed circuit board and a plurality of bonded tape carrier packages, each having a conductive lead thermocompression bonded to a corresponding conductive land on the [[and]] printed circuit board, the method comprising:

arranging the tape carrier packages along a common axis such that the respective leads thereof are disposed parallel to and spaced apart from each other at respective first intervals;

forming a plurality of the first conductive lands pattern group on the printed circuit board, the lands being arranged along a common axis and disposed parallel to and spaced apart from each other at respective second intervals determined in accordance with the thermal expansion properties of the printed circuit board such that, in a pre-compression bonded state, the respective second intervals between adjacent ones of the first conductive lands pattern group are smaller than the respective first intervals between adjacent ones of the corresponding tape carrier package leads;

thermocompression bonding the respective leads of the tape carrier packages to corresponding ones of the lands on [[and]] the printed circuit board; and,

during the thermocompression bonding, allowing the printed circuit board to expand such that the respective lands are first conductive pattern group is substantially aligned with corresponding ones of the leads of second conductive pattern group provided on the tape carrier packages.

16. (cancelled)

17. (currently amended) The method of claim 15, further comprising, measuring the thermal expansion properties of the printed circuit board before forming the leads thereon said forming, measuring the thermal expansion properties of the printed circuit board.

18. (currently amended) The method of claim 15, wherein the respective second intervals between adjacent ones of the leads first conductive pattern group are asymmetric with respect to a line passing through the middle of a width of the printed circuit board when the printed circuit board is asymmetric with respect to said line.

19. (currently amended) A printed circuit board adapted that is to be electrically connected to an external device through a plurality of tape carrier packages, each having a conductive lead group disposed parallel to and spaced apart from adjacent lead groups at first intervals each other, the printed circuit board comprising:

a substrate; and,

a plurality of printed circuit board conductive land groups formed on the substrate and disposed parallel to and spaced apart from each other at second intervals, each one of the printed circuit board land group[[s]] corresponding one to one with to a respective one of the conductive leads of the tape carrier packages, wherein the second intervals are respectively smaller than the first intervals an interval between the printed circuit board land groups being smaller than an interval between the tape carrier packages.

20. (cancelled)

21. (currently amended) The printed circuit board of claim 19, wherein the second intervals between the printed circuit board land groups respectively become[[s]] substantially the same as the second intervals of the tape carrier packages by thermal expansion when the printed circuit board undergoes a thermo-compression bonding process.

22. (currently amended) The tape carrier package of claim 19, wherein the second intervals are between the printed circuit board land groups is asymmetric with respect to a line passing through a midpoint of a width of the printed circuit board when the printed circuit board is asymmetric with respect to said line.

23. (previously presented) A method of manufacturing a printed circuit board that is to be electrically connected to an external device through a plurality of tape carrier packages spaced apart from each other, comprising:

forming printed circuit board land groups that correspond one-to-one with each of the tape carrier packages on a substrate such that an interval between the printed circuit board land groups is smaller than an interval between the tape carrier packages.

24. (previously presented) The method of claim 23, wherein the interval between the printed circuit board land groups is determined by:

measuring an amount of total thermal expansion of the substrate under a thermo-compression bonding process, and

obtaining the interval between the printed circuit board land groups by considering the amount of total thermal expansion.

25. (new) The method of claim 15, wherein each conductive lead comprises a group of parallel, spaced conductive leads, and each conductive land comprises a corresponding group of parallel, spaced conductive lands.